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RQK0605JGDQA

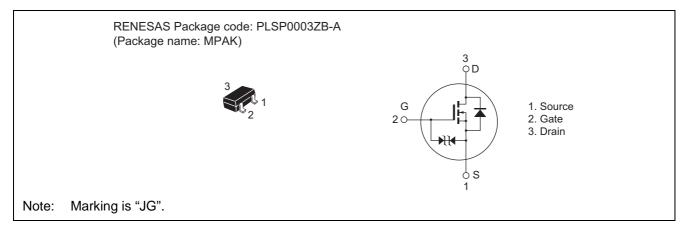
Silicon N Channel MOS FET Power Switching

> REJ03G1278-0400 Rev.4.00 Jun 15, 2006

Features

- Low on-resistance $R_{DS(on)} = 82 \text{ m}\Omega \text{ typ } (V_{GS} = 10 \text{ V}, I_D = 1.5 \text{ A})$
- Low drive current
- High speed switching
- 4.5 V gate drive

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	Ι _D	3.1	А
Drain peak current	I _{D(Pulse)} Note1	4.5	А
Body - drain diode reverse drain current	I _{DR}	3.1	А
Channel dissipation	Pch Note2	0.8	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. When using the glass epoxy board (FR-4: $40 \times 40 \times 1$ mm)



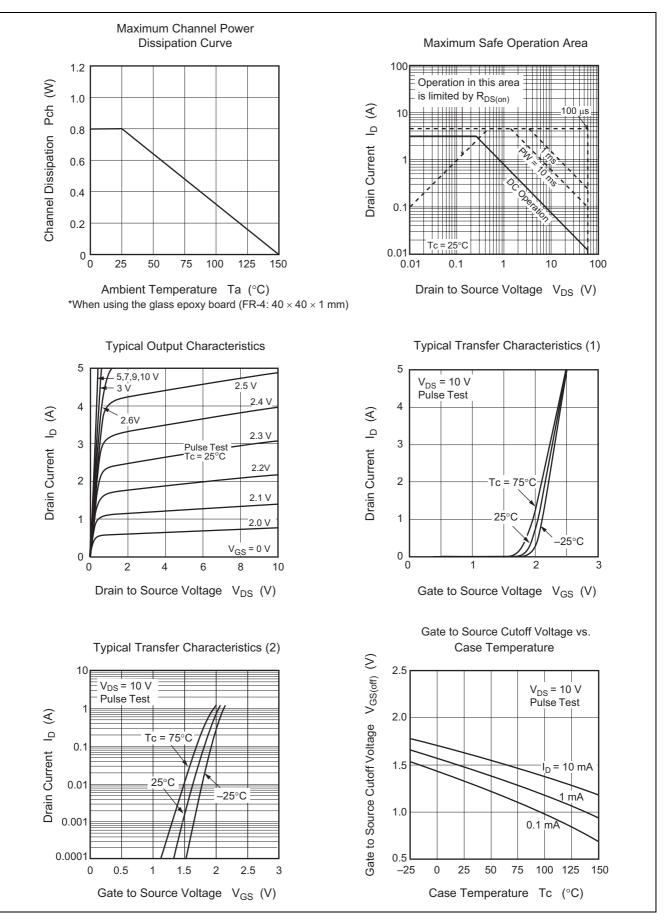
Electrical Characteristics

ltem	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	60	_	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_		±10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Drain to source leak current	I _{DSS}			1	μΑ	$V_{DS} = 60 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0		2.0	V	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$
Drain to source on state resistance	R _{DS(on)}	_	82	103	mΩ	$I_D = 1.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note3}}$
	R _{DS(on)}	_	93	131	mΩ	$I_D = 1.5 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	3.6	6	_	S	$I_D = 1.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss		405		pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	_	58	—	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	23	_	pF]
Turn - on delay time	t _{d(on)}	_	14	—	ns	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	tr	_	43	—	ns	$R_L = 10 \Omega$, $Rg = 4.7 \Omega$
Turn - off delay time	t _{d(off)}	_	43	—	ns	
Fall time	t _f	_	3.7	—	ns	
Total gate charge	Qg	_	6.9	_	nC	$V_{DD} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V},$
Gate to source charge	Qgs	_	0.9	—	nC	I _D = 3.1A
Gate to drain charge	Qgd	_	0.8	—	nC	1
Body - drain diode forward voltage	V _{DF}		0.8	—	V	$I_F = 1.5 \text{ A}, V_{GS} = 0^{\text{Note3}}$

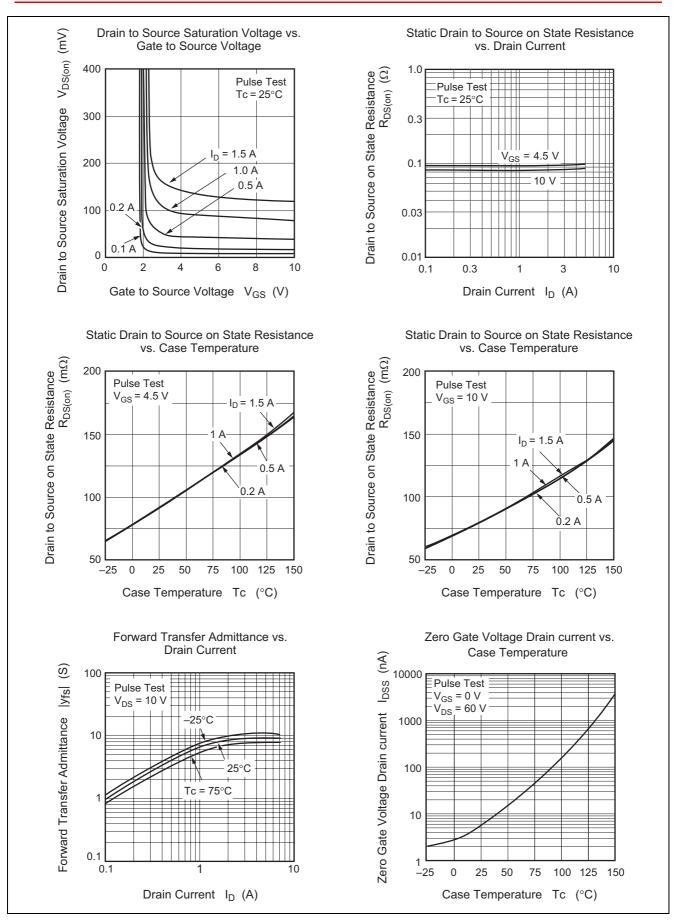
Notes: 3. Pulse test



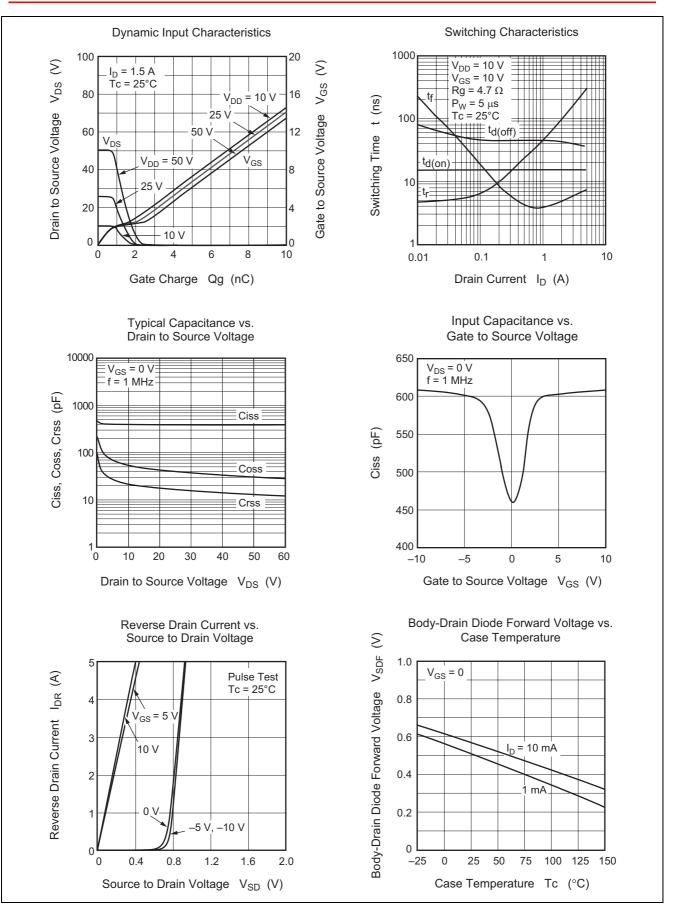
Main Characteristics





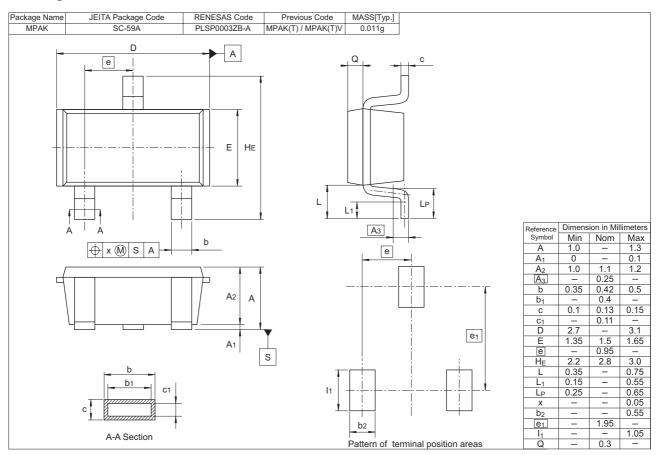








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container		
RQK0605JGDQATL-E	3000 pcs.	φ178 mm reel, 8 mm Emboss taping		



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